

AMENDMENTS TO THE ABSTRACT

**Please replace the original abstract with the enclosed replacement abstract provided
on a separate sheet.**

ABSTRACT

A method for manufacturing a printed wiring board, ~~including the steps of:~~ including forming a thermosetting resin layer ~~so as to fill the spaces between circuit patterns formed on the~~ printed wiring board; heating and curing the resin layer; and then polishing the cured resin layer ~~covering the circuit patterns~~, thereby exposing the circuit patterns. Additionally, The ~~the~~ step of heating and curing ~~comprises the following~~includes steps: ~~step 1:~~ maintaining the resin layer at a non-curable temperature in a state where the resin layer is pressed via the smoothing plate in a reduced pressure chamber; ~~step 2:~~ heating the resin layer in the pressed state to a curing temperature; ~~step 3:~~ introducing outside air into the reduced pressure chamber with the pressed state and the curing temperature maintained; ~~step 4:~~ reducing the pressure applied to the smoothing plate with the curing temperature maintained; and ~~step 5:~~ cooling the resin layer.